

What is claimed is:

1. A method for packaging a multi-chip module, comprising the steps of:

5 (a) connecting connection terminals of a tape of an anisotropic conductive adhesive film, on which a circuit is patterned to bond pads of the chip by applying an adhesive on the tape;

10 (b) applying an adhesive on an upper surface of the chip, folding the tape and attaching the folded tape to the upper surface of the chip;

(c) forming a plurality of ball terminals on a lower surface of the tape, the ball terminals being electrically connected to the connection terminals of the tape;

15 (d) manufacturing a plurality of individual chip scale packages by repeating the steps (a) to (c); and

(e) laminating the individual chip scale packages, wherein the ball terminals of an upper individual chip scale package is electrically connected to the circuit patterned 20 on the tape which covers a lower individual chip scale package.

2. The method of claim 1, further comprising the step of mounting the ball terminals of the lowest one of the 25 individual chip scale packages on a patterned circuit.

3. The method of claim 1, wherein, in the step (a), the chip is attached on the tape by applying an anisotropic conductive adhesive on the tape.

5 4. The method of claim 3, wherein the chip is connected to the tape by using a C4 process.

5. The method of claim 1, wherein, in the step (b), the tape is attached to the chip by applying an anisotropic
10 conductive adhesive to the upper surface of the chip.

6. The method of claim 1, wherein the tape covers only a lower surface of the uppermost one of the individual chip scale packages.